CBC3 Progress







Updated Technical Spec Document

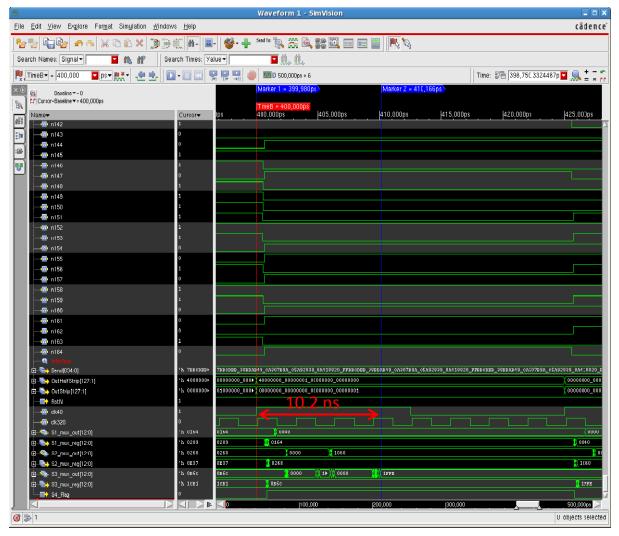
| | A second se | 1.0.0 |
|------------------------------|--|--------------|
| | Aug 25 th Contents page added. 2015 Page Numbers Added. | 1 & 2 All |
| CBC3 Technical Specification | Block diagram updated to include Layer Swap Logic & identify different | 3 |
| ebes recinical specification | | 2 |
| | signal types. | - |
| Author: Mark Prydderch | Layer Swapping Logic: Diagram added & text re-written for clarity. | 7 |
| | Stub-finding Logic: Additional diagram added & text re-written for clarity. | |
| | Stub gathering Logic: Diagram updated & extra one added for clarity. Text | 11 & 12 |
| Issue: 1.1 | added regarding priority. Bend LUT: Note added | 14 |
| | | 14 |
| Published: 25/08/15 | L1 Counter: Diagram removed. | |
| | Data Assembly and Output Logic: Text modified to expand on error flags. | 15 & 16 |
| | Diagram of serial data stream added. Note added regarding gaps in serial data. | |
| | Section added for Serial Fast Command Interface. | 16 |
| | Section added for Senar Past Command Interface. | 10 |
| | 40MHz Test Mode: Text updated for clarity. | 18 |
| | Delay Locked Loop: Text updated for clarity. | 18 |
| | SEU Immunity: Section title changed & text updated for clarity. | 18 |
| | External Interfaces: Serial Fast Command section modified. Added text & | 18 & 19 |
| | diagram to Inter-chip signals section. | 10 0 15 |
| | Analogue Biases: Section moved to later in document. Sections added for | 20 |
| | Post-Amp reference voltages and Bandgap. | 20 |
| | July 17th 2015 Note on detector capacitance assumptions | 4 |
| | March 9 th Updated to include statement relating to the bend code definition, where | 8 |
| | 2015 a spare binary code 10000 is assigned to null event coding. | |
| | Correction of Power Specification Target to 450 µW/Channel. | |
| | | |

Post Design Review actions

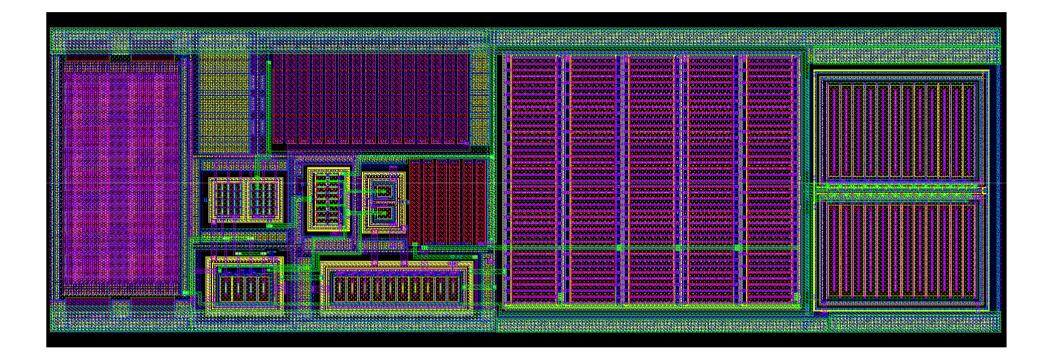
Worst case Propagation for Stub Gathering Logic (SGL): 10.2ns

(1 stub on 0 and 1 stub on half stub 127, with a mid range stub active on half stub 65.)

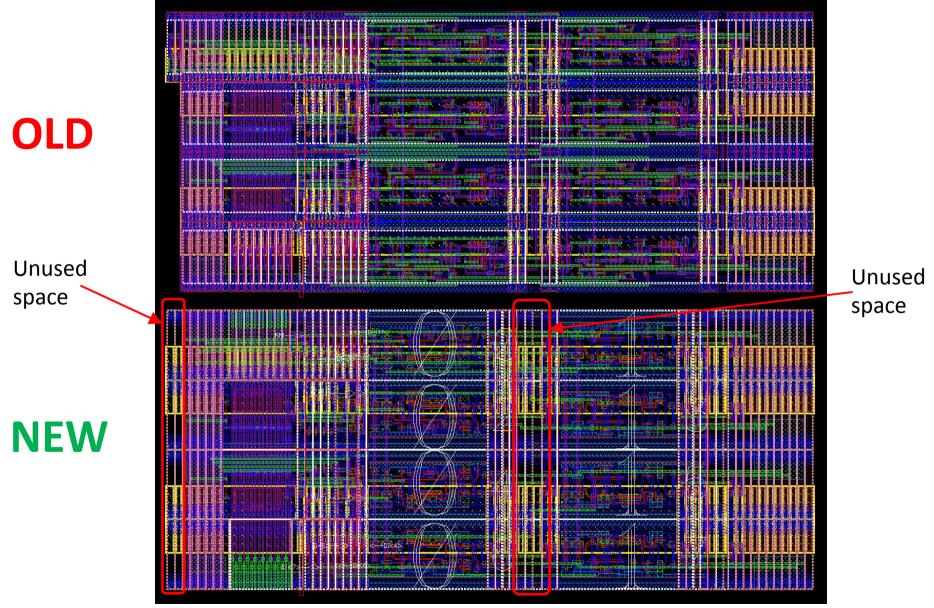
Dynamic Power Dissipation for SGL: 7.62mW (with 3 stubs every 25ns)



Current Reference layout complete

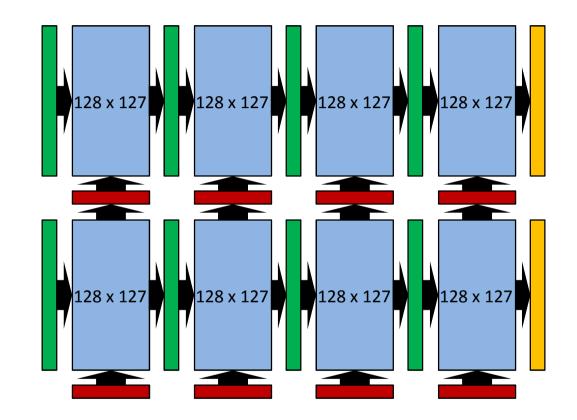


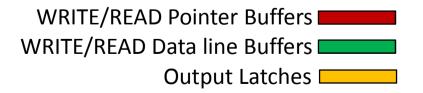
New I2C register



Same footprint as old cell for direct swap out.

Pipeline





Summary

- Technical Specification document Updated to Version 1.1.
- Current reference circuit layout completed.
- I2C Register Layout modified to replace the TRL with the Whitaker latch.
- SRAM simulated: Buffer sizes and architecture decided following simulation and re-sizing of the READ & WRITE transistors in the cell.
- Post Design Review actions ongoing.
- Provision of Top level code to IPNL On hold for minor changes.